

WHAT IS CLAIMED IS:

1. A solder-bearing article comprising:

a body having a first face, a second face, and a plurality of openings formed therein; and

a solder mass securely held by the body, the solder mass having a first section disposed along the first face such that the solder mass is disposed over at least some of the plurality of openings, the solder mass having a second section disposed along the second face and in the form of at least one rivet head that forms a part of a solder rivet that extends through one opening from the first face and serves to securely hold the solder mass on the body.

2. The solder-bearing article of claim 1, wherein the solder mass is a solder wire that extends along one edge of the body.

3. The solder-bearing article of claim 1, wherein the solder-bearing component is selected from the group consisting of: a lead, a terminal, an electrical connector, and an electromagnetic shield.

4. The solder-bearing article of claim 1, wherein the solder mass disposed along the second face has a series of recessed portions that are axially aligned with the plurality of openings.

5. The solder-bearing article of claim 1, wherein the head has a hemispherical shape.

6. The solder-bearing article of claim 1, wherein the plurality of openings is formed at a lower edge of the body.

7. The solder-bearing article of claim 1, wherein the plurality of openings is formed in an medial section of the body.

8. The solder-bearing article of claim 1, wherein the solder mass has a plurality of rivet heads that are associated with a plurality of solder rivets that extends through a plurality of the openings and serve to securely hold the solder mass on the body.

9. A solder-bearing article comprising:
a body having a first face, a second face, and a plurality of slots formed therein; and

a solder mass securely held by the body, the solder mass having a first section disposed along the first face such that the solder mass is disposed over at least some of the plurality of slots, the solder mass being deformed so that a plurality of rivet heads are formed along the second face, the rivet heads being part of a plurality of solder rivets that extend through preselected slots from the first face and serve to securely hold the solder mass on the body.

10. The solder-bearing article of claim 9, wherein the plurality of slots are formed along one edge of the body and are open along the one edge.

11. A method of retaining a solder mass within a solder-bearing article having a first face and a second face, the method comprising the steps of:

- forming a plurality of openings in the solder-bearing article;
- disposing a length of solder mass along the first face such that the solder mass is disposed over at least some of the plurality of openings; and
- forming a plurality of solder rivets by compressing sections of the solder mass into at least some of the plurality of openings such that each solder mass section extends through the opening and beyond the second face to form one solder rivet resulting in the solder mass being securely carried by the solder-bearing article.

12. The method of claim 11, wherein the step of forming the

solder rivets includes the steps of:

positioning a tool relative to a section of the solder mass that extends across the opening;

driving the tool into the solder mass section so as to cause the solder mass section to be compressed into the opening, the solder mass section being driven until at least a portion of the solder mass extends beyond the second face to form the solder rivet; and

retracting the tool from the solder mass.

13. The method of claim 11, further including the step of:

positioning a die proximate to the second face such that one die cavity is aligned with each opening in which a solder rivet is to be formed, the die cavity having a shape that forms a rivet head.

14. The method of claim 13, wherein the die cavity is shaped to form a hemispherical rivet head.

15. The method of claim 12, wherein the tool is an elongated mandrel having a diameter less than a diameter of the opening.

16. The method of claim 12, wherein the tool is an elongated mandrel having a diameter greater than a diameter of the opening.

17. The method of claim 11, further including the step of:
coining the solder mass after the plurality of solder rivets.

18. The method of claim 11, wherein the solder mass comprises
a length of solder wire.

19. The method of claim 11, wherein the solder mass provides at
least one of a structural connection and an electrical connection between the
solder-bearing article and another article.